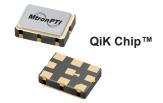


Product Features

- Multiple Output Frequencies (2, 3, or 4) Selectable
- QiK Chip™ Technology
- Superior Jitter Performance (less than 0.25 ps RMS, 12 kHz 20 MHz)
- SAW replacement better performance
- Frequencies from 50 MHz 1.4 GHz (LVDS/LVPECL/CML)
- Frequencies from 10 MHz 150 MHz (HCMOS)





Product Description

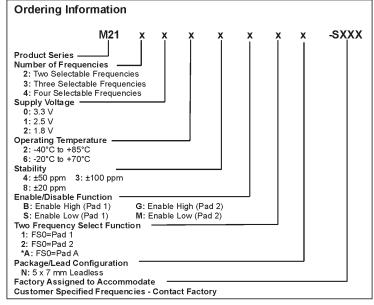
The multiple frequency oscillator utilizes MtronPTI's Qik Chip[™] technology to provide a very low jitter clock for all output frequencies. The M21x is available with up to 4 different frequency outputs from 10MHz through 1.4 GHz. The M21x utilizes the stable fundamental 3rd overtone crystal and the Qik Chip[™] IC to provide the wide range of output frequencies. Using this design approach, the M21x provides exceptional performance in frequency stability, jitter, phase noise and long term reliability.

Product Applications

- Global/Regional selection
- Forward Error Correction (FEC) / Selectable Functionality applications
- Telecommunications such as SONET / SDH / DWDM / FEC / SERDES / OC-3 thru OC-192
- 1-2-4-10 Gigabit Fibre Channel
- Wireless base stations / WLAN / Gigabit Ethernet

- xDSL, Network Communications
- Avionic flight controls
- Military communications
- Clock and data recovery
- Low jitter clock generation
- · Frequency margining

Product Ordering Information



Frequency Select Truth Table							
FS1 FS0							
Frequency 1	High	High					
Frequency 2	High	Low					
Frequency 3	Low	High					
Frequency 4	Low	Low					

NOTE: Logic Low = 20% Vcc max. Logic High = 80% Vcc min.

^{*}For three and four frequency selections, FS0=Pad A



Performance Characteristics

	PARAMETER	Symbol	Min.	Тур.	Max.	Units	Condition/Notes			
	Frequency Range	F	50	1	1400	MHz	LVPECL/LVDS/CML - See Note 1			
			10		150		HCMOS			
	Operating Temperature	TA		-20 to +7	0	°C	Customer Specified			
				-40 to +8	5	°C	Sustomer Opecined			
	Storage Temperature	Ts	-55		+125	°C				
	Frequency Stability	∆F/F	See (Ordering Inf	ormation	ppm	See Note 2			
	Aging	1								
	1st Year		-3		+3	ppm				
	Thereafter (per year)		-1		+1	ppm				
	Supply Voltage	Vcc	1.71	1.8	1.89	V				
			2.375	2.5	2.625	V				
			3.135	3.3	3.465	V				
	Input Current	Icc			125	mΑ	LVPECL/HCMOS/CML			
					105	mA	LVDS			
	Load						See Note 3			
			50 Ohms to (Vcc -2) Vdc 100 Ohm differential load				LVPECL Waveform LVDS/CML Waveform			
					15	pF	CMOS Waveform			
Suc	Symmetry (Duty Cycle)		45		55	%	LDPECL: Vdd – 1.3 V			
Ĭ	, , , , ,	<u> </u>	1		1 33	/*	LVDS: 1.25 V			
≌	Output Skew			20		ps	LVPECL			
딩				15		ps	CML			
읈				20		ps	LVDS			
<u>ē</u>	Differential Voltage	Vod	250	350	450	mV	LVDS			
Ĭ		Vod	0.7	0.95	1.20	Vpp	CML			
Electrical Specifications	Common Mode Output Voltage	Vcm		1.2		٧	LVDS			
	Logic "1" Level	Voh	Vcc -1.02			V	LVPECL			
			90% Vdd				HCMOS			
1	Logic "0" Level	Vol			Vcc -1.63	V	LVPECL			
					10% Vdd		HCMOS			
	Rise/Fall Time	Tr/Tf		0.23	0.35	ns	@ 20/80% LVPECL			
		<u> </u>	<u> </u>	6.0 ns		ns	Ref. 10%-90% Vdd HCMOS			
	Enable Function Option B				Output active ables to high-Z	Customer Specified				
	Enable Function		0.5V max			Customer Specified				
	Option S				disables to hig	Custoffiel Specified				
	Tristate Function				ting: output act	Customer Specified				
			Input Logic	"0": output	t disables to hi	Custoffiel Specified				
	Frequency Selection		See Truth							
	Settling Time				10	ms	To within ± 1 ppm of frequency			
	Start up Time				10	ms				
	Phase Jitter									
	@ 622.08 MHz	фЈ		0.25		ps RMS	LVPECL/LVDS/CML Integrated 12 kHz – 20 MHz			
	@ 125 MHz				0.50	ps RMS	HCMOS (12 kHz – 20 MHz)			
<u></u>	Mechanical Shock			ration, ½ sinewave)						
<u>.</u>	Vibration	Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)								
ξl	Hermeticity	Per MIL-STD-202, Method 112, (1x10° atm. cc/s of Helium)								
ş۱	Thermal Cycle	Per MIL-STD-883, Method 1010, Condition B (-55°C to +125°C, 15 min. dwell, 10 cycles)								
Environmental	Solderability	Per EIAJ-S			,		,			
	Max. Soldering Cond.	See solder	profile, Figur	e 1						

Note 1: Contact factory for standard frequency availability over 945 MHz.

Note 2: Stability is inclusive of initial tolerance, deviation over temperature, shock, vibration, supply voltage, and aging for one

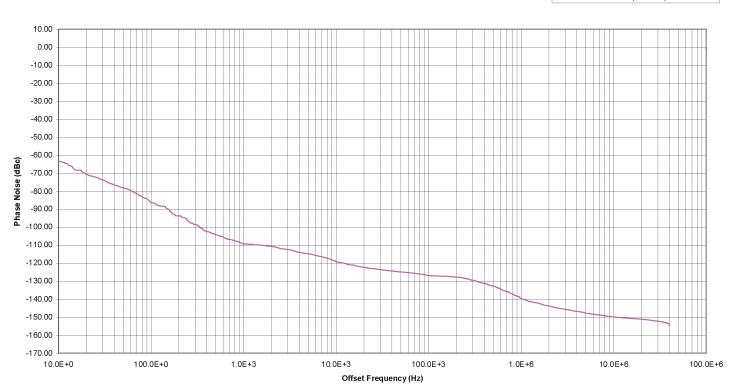
year at 50°C mean ambient temperature.

Note 3: See Load Circuit Diagram in this datasheet. Consult factory with nonstandard output load requirements.

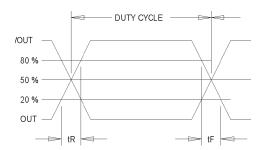


Phase Noise Plot

Phase Noise (dBc/Hz) 622.08MHz



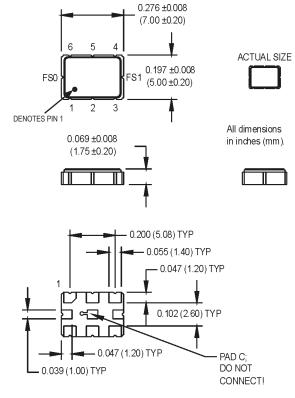
Output Waveform



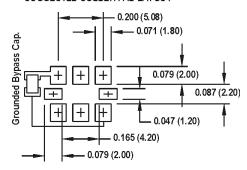
Output Waveform: LVDS/CML/LVPECL



Product Dimension & Pinout Information



SUGGESTED SOLDER PAD LAYOUT



PAD 1 ENABLE

Pad1: Enable/Disable or Tristate

Pad2: N/C or FS0

Pad3: Ground

Pad4: Output Q (LVPECL, LVDS, CML, HCMOS)

Pad5: Output Q (LVPECL, LVDS, CML) N/C for HCMOS

Pad6: Vcc

PadA: FS0 or N/C

PadB: FS1

PadC: Do not connect!

PAD 2 ENABLE

Pad1: N/C or FS0

Pad2: Enable/Disable or Tristate

Pad3: Ground

Pad4: Output Q (LVPECL,LVDS,CML,HCMOS)

Pad5: Output Q (LVPECL, LVDS, CML) N/C for HCMOS

Pad6: Vcc

PadA: FS0 or N/C

PadB: FS1

PadC: Do not connect!



Handling Information

Although protection circuitry has been designed into the M21x oscillator, proper precautions should be taken to avoid exposure to electrostatic discharge (ESD) during handling and mounting. MtronPTI utilizes a human-body model (HBM) and a charged-device model (CDM) for ESD-susceptibility testing and protection design evaluation. ESD voltage thresholds are dependent on the circuit parameters used to define the mode. Although no industry-wide standard has been adopted for the CDM, a standard HBM (resistance = 1500 Ω , capacitance = 100 pF) is widely used and therefore can be used for comparison purposes. The HBM ESD threshold presented here was obtained using these circuit parameters.

Model	ESD Threshold, Minimum	Unit
Human Body	1500*	V
Charged Device	1500*	V

^{*} MIL-STD-833D, Method 3015, Class 1

ATTENTION Static Sensitive Devices Handle only at Static Safe Work

Quality Parameters

Environmental Specifications/Qualification Testing Performed on the M21x Clock Oscillator							
Test	Test Method	Test Condition					
Electrical Characteristics	Internal Specification	Per Specification					
Frequency vs. Temperature	Internal Specification	Per Specification					
Mechanical Shock	MIL-STD-202, Method 213, C	100 g's					
Vibration	MIL-STD-202, Method 201-204	10 g's from 10-2000 Hz					
Thermal Cycle	MIL-STD-883, Method 1010, B	-55 Deg. C to +125 Deg. C, 15 minute Dwell, 10 cycles					
Aging	Internal Specification	168 Hours at 105 Degrees C					
Gross Leak	MIL-STD-202, Method 112	30 Second Immersion					
Fine Leak	MIL-STD-202, Method 112	Must meet 1x10 ⁻⁸					
Solderability	MIL-STD-883, Method 2003	8 Hour Steam Age – Must Exhibit 95% coverage					
Resistance to Solvents	MIL-STD-883, Method 2015	Three 1 minute soaks					
Terminal Pull	MIL-STD-883, Method 2004, A	2 Pounds					
Lead Bend	MIL-STD-883, Method 2004, B1	1 Bending Cycle					
Physical Dimensions	MIL-STD-883, Method 2016	Per Specification					
Internal Visual	Internal Specification	Per Internal Specification					

Part Marking Guide

Line 1: Model Number Line 2: Frequency Line 3: Date Code

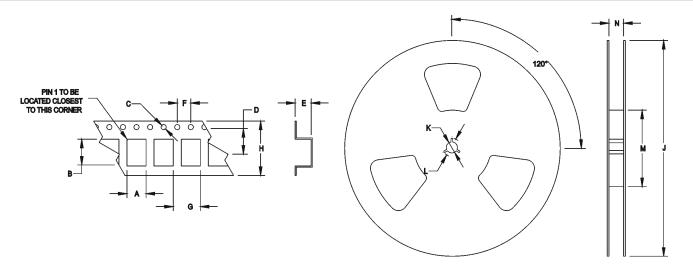
Line 4: Pin 1 Indicator / MtronPTI





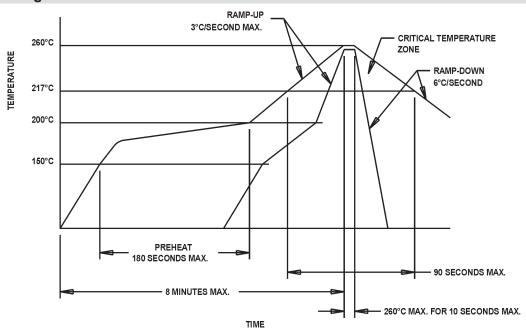
Tape & Reel Specifications

(all measurements are in mm)	Α	В	С	D	E	F	G	Н	I	J	K	L
M21x	6.51	9.29	1.5	7.5	2.8	4	8/12	16	180-330	13	21	60-100



Standard Tape and Reel: 1000 parts per reel

Maximum Soldering Conditions

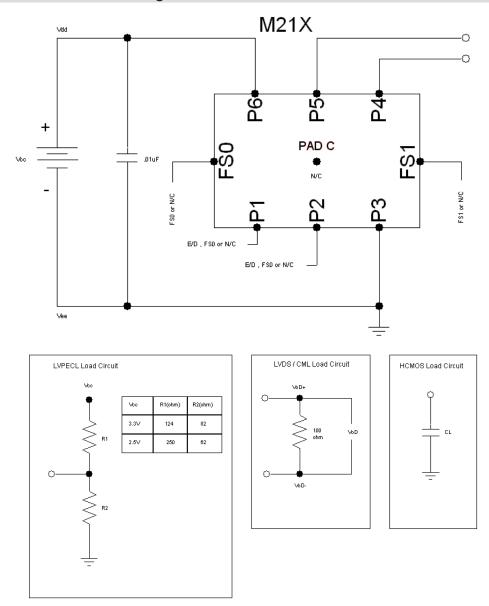


Solder Conditions

Note: Exceeding these limits may damage the device.



Typical Test Circuit & Load Circuit Diagrams



Product Revision Table

Date	Revision	PCN Number	Details of Revision
7/20/07	Α	10118	IC Revision to improve phase noise and electrical performance

For custom products or additional specifications contact our sales team at 800.762.8800 (toll free) or 605.665.9321

For more information on this product visit the MtronPTI website at www.mtronpti.com